

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Packaging	Typical Dimension mm(inches)
1	IC1	1	—	TLP7820	TOSHIBA	Isolation amplifier	SO8L	11.05 x 5.85
2	IC2	1	—	OPA237UA	TI	Operational amplifier	SOIC	6.0 x 4.9
3	R1	1	750Ω	—	—	0.25W, ±5%	—	3.2 x 1.6 (1206)
4	R2	1	750kΩ	—	—	800V, 0.25W, ±0.5%	—	6.3 x 3.1 (2512)
5	R3	1	750kΩ	—	—	800V, 0.25W, ±0.5%	—	6.3 x 3.1 (2512)
6	R4, R5, R6, R7	4	10kΩ	—	—	0.25W, ±0.5%	—	2.0 x 1.25 (0805)
7	R8, R9	2	1kΩ	—	—	0.25W, ±0.5%	—	2.0 x 1.25 (0805)
8	C1	1	0.5pF	—	—	Ceramic, 50V, ±10%	—	1.0 x 0.5 (0402)
9	C2, C3, C6	3	100nF	—	—	Ceramic, 25V, ±10%	—	2.0 x 1.25 (0805)
10	C4, C5	2	75pF	—	—	Ceramic, 100V, ±5%	—	1.6 x 0.8 (0603)
11	C7	1	10μF	—	—	Ceramic, 16V, ±10%	—	2.0 x 1.25 (0805)

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